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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/468,015	12/20/1999	DIETMAR EGGERT	F71989US	3122
23720 7	7590 07/20/2005		EXAMINER	
-	MORGAN & AMER	SON, P.C.		

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Please find below and/or attached an Office communication concerning this application or proceeding.





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APPLICATION NO./ CONTROL NO.	FILING DATE	FIRST NAMED INVENTOR / PATENT IN REEXAMINATION	ATTORNEY DOCKET NO.		
				EXAMINER	
			ART UNIT	PAPER	
				507	

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner for Patents

See attached sheet(s)

Kim Huynh Primary Examiner Art Unit: 2182

Application/Control Number: 09/468,015

Art Unit: 2182

NOTIFICATION OF NON-COMPLIANCE WITH THE REQUIREMENTS OF 37 CFR
1.192(c)

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The examiner agrees with the applicant that there is no amendment to the claims after the final rejection mailed since 9/02/03. Attached appendix A is a marked up copy of the claims amended submitted in an after final amendment in filed 9/9/02 which was enter per RCE filed 10/7/02. No amendment was made to any of the claims since the entry of the above mentioned amendment. Claim 1 includes the limitation "at least one via for forming an inductor coil for generating an inductance for said low pass filter" which is not part of the record. This limitation is not part of the finally rejected claim.

The applicant is requested to clarify which amendment introduces this limitation into the claim 1.

Please note the entry of request for consideration filed 2/9/05 simply entered the argument against the rejection as presented in the final rejection mailed 12/3/04 since the request for consideration indicated that no amendment has been made to the claims. Note also that paragraph 1 of the final rejection mailed 12/3/04 is inadvertently included from the previous office action. No new ground of rejection was made in the final rejection mailed 12/3/04.

The brief does not contain a statement of Grouping of Claims. Absence of such statement is a concession by the applicant that, if the ground of rejection were sustained as to any one of the rejected claims, it will be equally applicable to all of them

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claims are separately patentable.

Art Unit: 2182

(MPEP 1206 and CFR 1.193 (c)(7). CFR 1.193(c)(7) states the brief shall contain Grouping of Claims. For each ground of rejection which appellant contests and which applies to a group of two or more claims, the Board shall select a single claim from the group and shall decide the appeal as to the ground of rejection on the basis of that claim alone unless a statement is included that the claims of the group do not stand or fall together and, in the argument under paragraph (c)(8) of this section, appellant explains why the claims of the group are believed to be separately patentable. Merely pointing out differences in what the claims cover is not an argument as to why the

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APPENDIX A

- 1. (Twice Amended) An electrostatic discharge (ESD) protection network, comprising:
 - an inductor having a plurality of turns in the shape of a coil, the plurality of turns having an inductance; and
 - a plurality of electrostatic discharge (ESD) clamp devices, each one of said plurality of ESD clamp devices having a parasitic capacitance, said plurality of ESD clamp devices being connected to a corresponding one of said plurality of [the] turns of said inductor, the inductance of said turns and the parasitic capacitance of said ESD clamp devices thereby forming a low pass filter.
- 4. (Amended) An integrated circuit apparatus having an electrostatic discharge (ESD) protection network, said apparatus comprising:
 - an integrated circuit substrate;
 - a first insulation layer over a face of said integrated circuit substrate;
 - a plurality of conductive layers, each of the plurality of conductive layers in the shape[d] of a coil turn, the coil turn having a first and second end;
 - a plurality of insulation layers interleaved between the plurality of conductive layers;
 - a one of said plurality of conductive layers proximate to said first insulation layer and the other ones of said plurality of conductive layers stacked over the one with said plurality of insulation layers interleaved therebetween;

- a plurality of vias in the plurality of insulation layers, the plurality of vias connecting adjacent ones of the coil turns of said plurality of conductive layers, thereby forming an inductor coil; and
- a plurality of electrostatic discharge (ESD) clamp devices, each one of said plurality of ESD clamp devices having a parasitic capacitance, said plurality of ESD clamp devices being connected to a corresponding one of the [inductor] coil turns of said plurality of conductive layers, thereby forming a low pass filter.
- 18. (Amended) A method for providing an electrostatic discharge (ESD) protection network, comprising [the steps of]:
 - forming a plurality of conductive layers and a plurality of insulation layers, wherein said plurality of conductive [of] layers and said plurality of insulation layers are interleaved, wherein each of the conductive layers is formed in the shape[d] of a coil turn [of a coil] having an inductance such that such that each of the coil turns has a first and a second end;
 - forming a plurality of vias in said plurality of insulation layers, the plurality of vias being located between the ends of adjacent coil turns wherein conductive material is formed in said plurality of vias thereby connecting the first end of one coil turn to the second end of the adjacent coil turn;
 - providing a plurality of electrostatic discharge (ESD) clamp devices, each one of said plurality of ESD clamp devices having a parasitic capacitance; and

connecting said plurality of ESD clamp devices to a corresponding one of the coil turns of said plurality of conductive layers, thereby forming a low pass filter.